

Contents

1	Introduction	1
1.1	Electrical Interconnection Methods	1
1.2	The Wire Bonding Process	3
1.3	Measurement Approaches for Bonding Process Investigation	10
2	Sensor Design	13
2.1	Design Concept	13
2.1.1	Piezoresistivity	14
2.1.2	Symmetry Considerations	18
2.1.3	Stress Fields	28
2.1.4	Intrinsic Stress Fields	35
2.2	Ball Bond Sensor	36
2.2.1	XYZ-Force Sensor	38
2.3	Wedge Bond Sensor	46
3	Measurement System	49
3.1	Test Chip	49
3.2	Wire Bonding Signals and Measurement System	53
3.2.1	Ultrasonic System	61
4	Characterization	67
4.1	General Data	68
4.2	Sensor Calibration	68
4.2.1	Calibration with Shear Tester	69
4.2.2	Calibration with Gauge Weights	69
4.2.3	Calibration with Ultrasound Force Measurements	70
4.2.4	Noise	76
4.2.5	Sensor to Sensor Variations	76
4.2.6	Temperature Dependence of Sensitivity	78
4.3	Linearity	79
4.4	Placement Sensitivity	80
4.5	Offset	82
4.5.1	Temperature Coefficient of Offset	85
4.6	Summary of Technical Data of the Test Chip	92

5 Applications	93
5.1 Wire Bonder Development	94
5.1.1 Process Module Calibration	95
5.1.2 Bonding Speed Characterization	107
5.1.3 Long-Term Stability	112
5.2 Ball Bond Process Knowledge	115
5.2.1 Friction at Contact Zone	116
5.2.2 Friction Between Ball and Capillary	117
5.2.3 Deformation	122
5.2.4 Comparison with Other Measurement Methods	127
5.2.5 Bond Process Parameter Window	129
5.2.6 Comparison Between Au-Al and Au-Au Contacts	137
5.3 Wedge Bonding Process Knowledge	139
5.3.1 Tail Breaking Force	140
5.3.2 Gold - Gold Contact Bond	141
5.3.3 Gold - Aluminum Contact Bond	151
5.4 Flip-Chip Application	154
5.4.1 Thermal Cycling	155
6 Conclusions and Outlook	159
Abbreviations, Symbols, and Definitions.....	161
References.....	165
Subject Index	175